

D<sup>1</sup> amended.  
pad, and the first element surface being disposed in an opposite relation with respect to the first board surface;

a conductive connecting member disposed between the board wiring pad and the element wiring pad, and

a sealing member having a sealing portion, the sealing member only making contact with the first board surface over a contact area on the first board surface completely outside of a space formed between the first board surface and the first element surface with the sealing member being formed from a hot-melt material having a characteristic preventing the hot-melt material from spreading from the contact area into the space.

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D<sup>2</sup>  
168. (Thrice Amended) A surface acoustic wave device, comprising:

a printed circuit board of a material possessing a first region and a second region which is thicker than the first region, the second region including a board wiring pad thereon;

a surface acoustic wave element possessing a first element surface and a second element surface, the first element surface including a transducer portion, a element wiring pad and a surface acoustic wave absorbing member, and being disposed with a face-down so that the surface acoustic wave absorbing member is disposed in an opposite relation with respect to the first region of the printed circuit board;

a conductive connecting member disposed between the board wiring pad and the element wiring pad, and

a sealing member having a sealing portion, the sealing member only making contact with the first board surface over a contact area on the first board surface completely outside of a space formed between the first board surface and the first element surface with the sealing member being formed from a hot-melt material having a characteristic preventing the hot-melt material from spreading from the contact area into the space.

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170. (Thrice Amended) A surface acoustic wave device, comprising:

D<sup>3</sup> a printed circuit board including a first board surface and a second board surface, the first board surface having a board wiring pattern;

a surface acoustic wave element possessing a first element surface and a second element surface, the first element surface including a transducer portion, a element wiring pad and a surface acoustic wave absorbing member, and the first element surface being disposed in an opposite relation with respect to the first board surface;

a conductive connecting member disposed between the board wiring pattern and the element wiring pad, the conductive connecting member being composed of a plurality of bumps stacked according to a spacing between the board wiring pattern and the element wiring pad, and

a sealing member having a sealing portion, the sealing member only making contact with the first board surface over a contact area on the first board surface completely outside of a space formed between the first board surface and the first element surface with the sealing member being formed from a hot-melt material having a characteristic preventing the hot-melt material from spreading from the contact area into the space.

#### REMARKS

Favorable reconsideration of this application as presently amended and in light of the following discussion is respectfully requested.

Claims 166-171 are presently active in this application. Claims 166, 168, and 170 have been amended to better clarify the present invention without the introduction of any new matter.